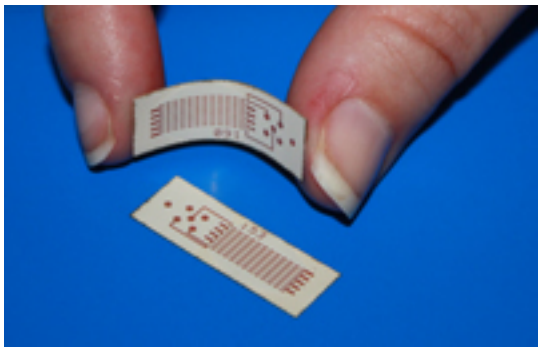
Combination of Materials, Fabrication and Test Expertise Deliver LCP Laminates with Exceptional Performance and Proven Reliability



Endicott Interconnect Technologies, Inc. (EI) announced recently that the company has added LCP Laminates to its family of microelectronics packaging product offerings. Custom designed LCP Laminates are suitable for semiconductor packages as LCP coreless designs for up to 6 layers as well as in combination with other rigid materials as hybrid circuits. Development and testing of Z-interconnect cross-sections for >8 layer offerings are also underway.

Long known for its expertise and know-how in the fabrication and testing of high performance materials, EI's innovative, adhesiveless, film-based LCP Laminates provide high density interconnection with proven reliability and performance. Beginning with Rogers ULTRALAM® 3000 series materials, EI fabricates, tests and assembles its LCP Laminates into advanced microelectronic packages including flex and chip-on-flex, offering a complete solution from design through test of the product.

The low dielectric constant and low dissipation factor of LCP provide superior electrical performance across a wide range of the RF spectrum and it remains stable even under harsh environmental conditions such as extreme temperature and humidity. Couple that with tolerance to high levels of radiation exposure, LCP becomes an excellent solution for Aerospace & Defense applications such as microwave and digital circuits for communications and radar, satellites, munitions and avionics.

Because it is biocompatible for use in the human body and near-hermetic due to low moisture absorption, LCP is also attractive for Medical applications such as implantable devices. When designs require the advantages of size, weight and power (SWaP) reduction and flexibility, EI LCP Laminates provide an excellent cost/performance ratio for users looking to make the jump from ceramic packages to an organic solution or any application requiring a system-in-package (SiP) approach.

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